
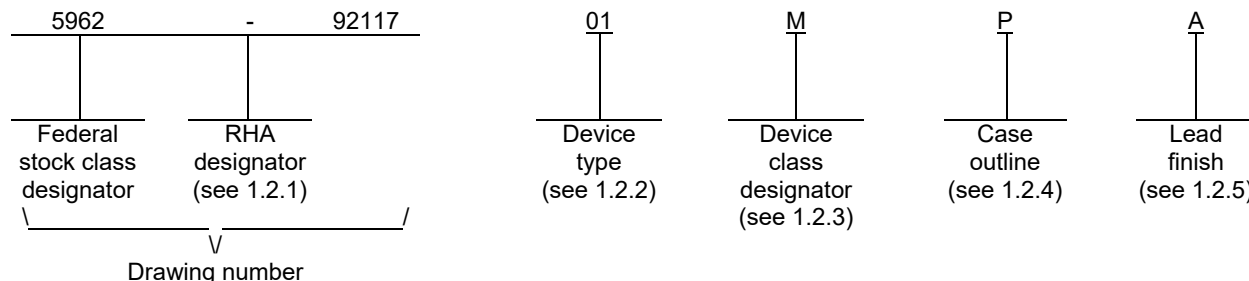


REVISIONS																		
LTR	DESCRIPTION											DATE (YR-MO-DA)				APPROVED		
A	<p>Sheet 3: Paragraph 1.3, Input common mode voltage range (<math>V_{CM}</math>), delete "<math>V_S</math>" and substitute "<math>\pm V_S</math>".</p> <p>Sheet 5: Table I, Quiescent power supply current test, <math>I_Q</math>, conditions column, delete "<math>V_S = \pm 5.0 V</math>" and substitute "<math>V_S = \pm 5.0 V, V_{OUT} = 0 V</math>" and delete "<math>V_S = \pm 15.0 V</math>" and substitute "<math>V_S = \pm 15.0 V, V_{OUT} = 0 V</math>".</p> <p>Sheet 8: Table I, Settling time test, <math>t_S</math>, delete subgroup "9" and substitute subgroup "4". Table I, Overshoot test, OS, delete subgroup "9" and substitute subgroup "4". Rise time test, <math>t_R</math>, delete subgroups "9, 10, 11" and substitute subgroups "4, 5, 6". Fall time test, <math>t_F</math>, delete subgroups "9, 10, 11" and substitute subgroups "4, 5, 6". Delete footnote "1" and substitute "1/ Unless otherwise specified, for dc tests, source resistance (<math>R_S</math>) &lt; 100 <math>\Omega</math>, load resistance (<math>R_L</math>) &gt; 100 k<math>\Omega</math>, and <math>V_{OUT} = 0 V</math>".</p> <p>Sheet 11: Table IIA, group A test requirements, delete "9, 10, 11 (five times). Group B endpoint electrical parameters, delete "9, 10, 11" (two times). Changes in accordance with N.O.R. 5962-R077-93.</p>											93-04-04				M. A. FRYE		
B	<p>Sheet 7: Table I. Slew rate test. Under the "Test" column, delete footnote "7" entirely. With the symbol of "SR-" and the condition of "<math>V_S = \pm 15 V</math>", delete the group A subgroup 4 value of "200 V/<math>\mu s</math>" and substitute "180 V/<math>\mu s</math>". Full power bandwidth test. Under the "Test" column, footnote "8" will be renumbered as footnote "7".</p> <p>Sheet 8: Table I. Delete footnote "7" entirely. Rise time test. Under the "Test" column, footnote "9" will be renumbered as footnote "8". Fall time test. Under the "Test" column, footnote "9" will be renumbered as footnote "8". Footnote "8" will be renumbered as footnote "7". Footnote "9" will be renumbered as footnote "8". Changes in accordance with N.O.R. 5962-R194-94.</p>											94-05-25				M. A. FRYE		
C	Drawing updated to reflect current requirements. - ro											01-09-10				R. MONNIN		
D	Drawing updated as part of 5 year review. -rrp											07-04-18				ROBERT M. HEBER		
E	Drawing updated to reflect current MIL-PRF-38535 requirements. - ro											13-09-12				C.SAFFLE		
F	Drawing updated to reflect current MIL-PRF-38535 requirements. - jch											20-01-27				JAMES R. ESCHMEYER		
																		
REV																		
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OF SHEETS			SHEET	1	2	3	4	5	6	7	8	9	10	11	12			
PMIC N/A			PREPARED BY RICK C. OFFICER					<b>DLA LAND AND MARITIME</b> <b>COLUMBUS, OHIO 43218-3990</b> <a href="https://www.dla.mil/LandandMaritime">https://www.dla.mil/LandandMaritime</a>										
<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A			CHECKED BY CHARLES E. BESORE															
			APPROVED BY MICHAEL A. FRYE															
			DRAWING APPROVAL DATE 92-06-16															
			REVISION LEVEL F															
					SIZE A	CAGE CODE <b>67268</b>			<b>5962-92117</b>									
					SHEET			1 OF 12										

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type. The device type identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	AD827	High speed, low power, dual operational amplifier

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings. <sup>1/</sup>

Supply voltage (Vs) .....	±18 V dc
Input common mode voltage range (VCM) .....	±Vs
Differential input voltage .....	±6.0 V dc
Internal power dissipation (PD):	
Case P .....	1.3 W <sup>2/</sup>
Case 2 .....	1.0 W <sup>2/</sup>
Storage temperature range .....	-65°C to +150°C
Lead temperature (soldering, 60 seconds) .....	+300°C
Junction temperature (T <sub>J</sub> ) .....	+175°C
Thermal resistance, junction-to-case (θ <sub>JC</sub> ) .....	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ <sub>JA</sub> ) .....	110°C/W

1.4 Recommended operating conditions.

Supply voltage range (Vs) .....	±4.5 V dc to ±15 V dc
Ambient operating temperature range (TA) .....	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil>.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

- <sup>1/</sup> Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- <sup>2/</sup> Maximum internal power dissipation is specified so that the junction temperature does not exceed +175°C. For case P, derate 9 mW/°C for TA > +32°C and for case 2, derate at 6.6 mW/°C for TA > +25°C.

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### 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit	
					Min	Max		
Input offset voltage	VOS	VS = ±5 V, VCM = 0 V	1	01		±2.0	mV	
			2,3			±4.0		
		VS = ±15 V, VCM = 0 V	1			±2.0		
			2,3			±5.0		
Input bias current	IIB	VS = ±5 V and ±15 V, VCM = 0 V	1	01		7.0	μA	
			2,3			9.5		
Input offset current	IOS	VS = ±5 V and ±15 V, VCM = 0 V	1	01		0.3	μA	
			2,3			0.4		
Output current <u>3/</u>	IOUT	VS = ±5 V, VOUT = ±2.5 V, TA = +25°C	4	01	16		mA	
		VS = ±15 V, VOUT = ±10 V, TA = +25°C			20			
Common mode input <u>4/</u> voltage range	VCM	VS = ±5 V	1,2,3	01	±2.5		V	
		VS = ±15 V			±12			
Quiescent power supply current	IQ	VS = ±5 V, VOUT = 0 V	1	01		13	mA	
			2,3			17.5		
		VS = ±15 V, VOUT = 0 V	1			13.5		
			2,3			18		
Quiescent power <u>5/</u> consumption	PQ	VS = ±5 V, VOUT = 0 V, IOUT = 0 mA	1	01		130	mW	
			2,3			175		
		VS = ±15 V, VOUT = 0 V, IOUT = 0 mA	1			405		
			2,3			540		
Power supply rejection ratio	PSRR	VS = ±5 V to ±15 V	1	01	75		dB	
			2,3			72		
Open loop gain	AOL	VS = ±5 V, RL = 500 Ω, VOUT = ±2.5 V	1	01	2.0		V/mV	
			2,3			1.0		
		VS = ±15 V, RL = 1.0 kΩ, VOUT = ±10 V	1			3.0		
			2,3			1.5		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Common mode rejection ratio	CMRR	VS = ±5 V, VCM = ±2.5 V	1	01	80		dB
			2,3		75		
		VS = ±15 V, VCM = ±12 V	1		80		
			2,3		75		
Output voltage swing	VOUT	VS = ±5 V, RL = 500 Ω	1	01	±3.0		V
			2,3		±2.5		
		VS = ±5 V, RL = 150 Ω	1		±2.5		
		VS = ±15 V, RL = 1 kΩ	1,2,3		±12		
		VS = ±15 V, RL = 500 Ω	1		±10		
Slew rate <u>3/ 6/</u>	+SR	VS = ±5 V, RL = 500 Ω, AV = +1.0, VOUT = -2 V to +2 V, rising edge, measured at 10 percent to 90 percent	4	01	120		V/μs
			5,6		90		
	-SR	VS = ±5 V, RL = 500 Ω, AV = +1.0, VOUT = +2 V to -2 V, falling edge, measured at 10 percent to 90 percent	4		90		
			5,6		65		
	+SR	VS = ±15 V, RL = 1 kΩ, AV = +1.0, VOUT = -5 V to +5 V, rising edge, measured at 10 percent to 90 percent	4		200		
			5,6		137		
	-SR	VS = ±15 V, RL = 1 kΩ, AV = +1.0, VOUT = +5 V to -5 V, falling edge, measured at 10 percent to 90 percent	4		180		
			5,6		137		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Differential input <u>3/</u> impedance	RIN	VCM = 0 V, VS = ±15 V, TA = +25°C	4	01	60		kΩ
Unity gain <u>3/</u> bandwidth	GBWP	VS = ±5.0 V, VOUT = ±100 mV, RL = 500 Ω, TA = +25°C, AV = 1	4	01	25		MHz
		VS = ±15 V, VOUT = ±100 mV, RL = 1 kΩ, TA = +25°C, AV = 1			40		
Full power <u>3/ 7/</u> bandwidth	FPBW	VS = ±5.0 V, VPK = 2.5 V, RL = 500 Ω, TA = +25°C	4	01	5.7		MHz
		VS = ±15 V, VPK = 10 V, RL = 1 kΩ, TA = +25°C			3		
Closed loop stable <u>3/</u> gain	CLSG	VS = ±5 V, ±15 V, RL = 1.0 kΩ	4,5,6	01	1		V/V
Settling time <u>3/</u>	ts	VS = ±15 V, RL = 1.0 kΩ, AV = -1, TA = +25°C, 10 V step at 0.1 percent of the fixed value	4	01		150	ns
Overshoot <u>3/</u>	OS	VS = ±15 V, RL = 1.0 kΩ, AV = 1, TA = +25°C, VOUT = 0 V to ±200 mV	4	01		30	%

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Rise time <u>3/ 8/</u>	t <sub>R</sub>	V <sub>S</sub> = ±5.0 V, ±15 V, R <sub>L</sub> = 1.0 kΩ, A <sub>V</sub> = 1, V <sub>OUT</sub> = 0 V to +200 mV	4,5,6	01		10	ns
Fall time <u>3/ 8/</u>	t <sub>F</sub>	V <sub>S</sub> = ±5.0 V, ±15 V, R <sub>L</sub> = 1.0 kΩ, A <sub>V</sub> = 1, V <sub>OUT</sub> = 0 V to -200 mV	4,5,6	01		10	ns

1/ Unless otherwise specified, for dc tests, source resistance (R<sub>S</sub>) < 100 Ω, load resistance (R<sub>L</sub>) > 100 kΩ, and V<sub>OUT</sub> = 0 V.

2/ The limiting terms “min” (minimum) and “max” (maximum) shall be considered to apply to magnitudes only. Negative current shall be defined as conventional current flow out of a device terminal.

3/ If not tested, shall be guaranteed to the limits specified in table I herein.

4/ This test is guaranteed by testing CMRR.

5/ Quiescent power consumption is based on quiescent supply current test maximum (no load outputs).

6/ Slew rate test limits are guaranteed after 5 minutes of warm up.

7/ Full power bandwidth = SR / (2πV<sub>PK</sub>).

8/ Rise and fall times are measured between 10 percent and 90 percent points.

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Device type	01	
Case outlines	P	2
Terminal number	Terminal symbol	
1	OUTPUT 1	NC
2	-INPUT 1	OUTPUT 1
3	+INPUT 1	NC
4	-Vs	NC
5	+INPUT 2	-INPUT 1
6	-INPUT 2	NC
7	OUTPUT 2	+INPUT 1
8	+Vs	NC
9	---	NC
10	---	-Vs
11	---	NC
12	---	+INPUT 2
13	---	NC
14	---	NC
15	---	-INPUT 2
16	---	NC
17	---	OUTPUT 2
18	---	NC
19	---	NC
20	---	+Vs

NC = No connection

FIGURE 1. Terminal connections.

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#### 4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

##### 4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

##### 4.2.1 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

##### 4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1/</u>	1,2,3,4,5,6 <u>1/</u>	1,2,3,4,5,6 <u>1/</u>
Group A test requirements (see 4.4)	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
Group C end-point electrical parameters (see 4.4)	1	1	1
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b.  $T_A = +125^\circ\text{C}$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.1 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

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4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , after exposure, to the subgroups specified in table II herein.

## 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

## 6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-92117</b>
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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 20-01-27

Approved sources of supply for SMD 5962-92117 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <https://landandmaritimeapps.dla.mil/programs/smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9211701MPA	24355	AD827SQ/883B
5962-9211701M2A	24355	AD827SE/883B

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

24355

Vendor name and address

Analog Devices  
 Route 1 Industrial Park  
 P.O. Box 9106  
 Norwood, MA 02062  
 Point of contact: 804 Woburn Street  
 Wilmington, MA 01887-3462

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.